

29/11/2000

EMAP 2000 Reveals Advances in Electronic Manufacturing

The Hong Kong University of Science and Technology (HKUST) will be hosting the first major international conference on electronic materials and packaging in Hong Kong from 30 November to 2 December 2000.

The [International Symposium on Electronic Materials and Packaging \(EMAP 2000\)](#) provides a forum for world-renowned authorities to exchange and discuss ideas on recent developments and state-of-the-art technologies in electronic materials, packaging and assembly. It is organized by HKUST's Department of Mechanical Engineering and [Electronic Packaging Laboratory \(EPACK Lab\)](#) in collaboration with the Institute of Electrical and Electronics Engineers Component, Packaging and Manufacturing Technology (IEEE-CPMT), Hong Kong Chapter.



Francis Ho speaks at the inaugural reception of EMAP 2000.

To mark the inauguration of EMAP 2000, a reception was held at HKUST today (29 November), attended by Mr Francis Ho, Commissioner for Innovation and Technology, and Prof Chia-Wei Woo, President of HKUST.

Prof Rao Tummala, Petit Chair Professor and Director of Packaging Research Center at Georgia Institute of Technology, presented his model for academic research and education at the ceremony, calling for a partnership between government, industry and the academia.

EPACK Lab also took the opportunity to express gratitude to its donors for their continuing support and sponsorship, and for promoting university-industry-government collaboration. Among the donors is Mr Chee Cheung, who founded Compass Technology. He is an ardent supporter of university research projects and has made contributions amounting to millions of dollars. The other donors are Advanced Interconnect Technologies HK, ASAT, ASM Assembly Automation, Astec power, Astron Group, Hua Ko Electronics, Philips EDL, Shipley Ronal Asia and Vtech Telecommunications. They were each presented as souvenir a silicon wafer assembled with thousands of tiny miniature metal balls made in the EPACK Lab, visible only under a microscope.

Details are as follows:

- Event: Donor Reception for HKUST EPACK Lab & Inaugural Reception for EMAP 2000
- Date: Wednesday, 29 November 2000
- Time: 5:30 pm
- Venue: Foyer, 7th floor, Academic Building, HKUST, Clear Water Bay, Kowloon (Lift nos. 13-15)

- Event: International Symposium on Electronic Materials and Packaging
- Date: 30 November-2 December 2000
- Time: 9 am-5:10 pm
- Venue: University Center, HKUST, Clear Water Bay, Kowloon
- Language: English

About EPACK Lab

Electronic packaging is the technology used for mounting semiconductor IC devices inside electronic products. It is a billion-dollar business that is growing every year with the increasing demand for the Internet and mobile gadgets. There is a large demand for local graduates to work in electronic packaging as well as a need for university support in technology transfer projects.

The HKUST EPACK Lab was established in 1998 under the umbrella of the Engineering Industrial Consortium (EIC). It is a facility to support electronic packaging programs at HKUST in both development and sustaining projects that will fulfill the current and future needs of the IC packaging industry in Hong Kong. Currently the EPACK Lab is the host of two Innovation & Technology Fund projects with grants of HK\$18 million dollars from the Innovation and Technology Commission of Hong Kong and local companies. In addition, it is conducting numerous research projects sponsored by the Research Grants Council and industrial grants. The activities in electronic packaging involve seven faculty members in the Department of Mechanical Engineering (Drs Jang Kyo Kim, David C C Lam, Ricky Lee, Steve H K Lee, Jingshen Wu, Matthew M F Yuen), and Prof Philip Chan in the Department of Electrical & Electronic Engineering.